# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Z27x G2</th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>HP Z27x G2 Display</td>
<td></td>
<td></td>
</tr>
<tr>
<td>HP DreamColor Z27x G2 Display</td>
<td></td>
<td></td>
</tr>
<tr>
<td>HP DreamColor Z27x G2 Studio Display</td>
<td></td>
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</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, SPS board</em>1, Control Board<em>1, SOC Board</em>1 (POS Sensor Board and AMS Sensor Board &lt;10 sq cm)</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries CR2032 Lithium Manganese Dioxide Battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>C631 in SPS Board</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DP cable<em>1, HDMI cable</em>1, USB3.0 cable<em>1, USB3.1-C cable</em>1, USB3.1-A/C cable<em>1, Power cord</em>1</td>
<td>6</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>2</td>
</tr>
<tr>
<td>Hexagon Screw Driver</td>
<td>0</td>
</tr>
<tr>
<td>Flathead screwdriver</td>
<td>1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove stand by quick release button to separate the stand and monitor head.
2. Use tool to separate rear cover from monitor head through tear down slot.
3. Use tool to release screw from bucket, then separate bucket and trim from monitor head by hand. Separate top corner first then pull up the bucket to separate bucket and SHD.
4. Use tool to release screws on SHD, then separate the SHD from monitor head, separate the mylar and thermal pad which on the SHD. Release two screws on the SHD to separate the release button and springs.
5. Tear the tape from lamp wire, motor wire, color sensor wire, then disassemble the lamp wire, motor wire, color sensor wire, LVDS FFC*4 and ctrl-BD FFC from connector.
6. Release screws on the power board and interface board, then disassemble power-BD and interface-BD from the chassis.
7. Separate the front bezel from the panel, then use tool to release screws to disassemble ctrl-BD and separate the button and lens from the bezel.
8. Tear the AL-tape on the middle-top side and release side mount screws(*4) to separate chassis and panel, then disassemble the LVDS FFC and lamp wire from the panel by hand.
9. Separate the colorimeter module from top side on the monitor head by hand.
10. To separate colorimeter module, release screw which on the bracket, then remove the motor, worm, arm. Disassemble the arm to the front and back cover and remove the color sensor board from the front cover. Remove the position sensor board from the bracket.
11. Remove the battery which is on the interface board.
12. Remove the gasket, thermal pad and tape on the chassis.
13. Use tool to release screws and separate base
14. Use tool to release screws and separate base cover.
15. Use tool to release screws and separate VESA from stand
16. Use tool to release screws and separate the back cover from stand.
17. Use tool to release screws and separate hinge module.
18. Use tool to release screws and separate QR button.
19. Use tool to release screws and separate lift POM and front cover.
20. Use tool to release screws and separate hinge shield.
21. Use tool to release screws and separate constant force springs from hinge shield.
22. Use tool to release screws and separate the site of constant force springs.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

2. Use tool to separate rear cover from monitor head through tear down slot.

3. Use tool to release screw from bucket, then separate bucket and trim from monitor head by hand. Separate top corner first then pull up the bucket to separate bucket and SHD.
5. Tear the tape from lamp wire, motor wire, color sensor wire, then disassemble the lamp wire, motor wire, color sensor wire, LVDS FFC*4 and ctrl-BD FFC from connector.
6. Release screws on the power board and interface board, then disassemble power-BD and interface-BD from the chassis.

8. Release side mount screws (*4) to separate SHD and panel, then disassemble the LVDS FFC and lamp wire from the panel by hand.
9. Separate the colorimeter module from top side on the monitor head by hand.

10. To separate colorimeter module, release screw which on the bracket, then remove the motor, worm, plastic arm. Disassemble the arm to the front and back cover and remove the color sensor board from the front cover. Remove the position sensor board from the bracket.
13. Use tool to release screws and separate base

14. Use tool to release screws and separate base cover.
15. Use tool to release screws and separate VESA from stand.

16. Use tool to release screws and separate the back cover from stand.

17. Use tool to release screws and separate hinge module.
18. Use tool to release screws and separate QR button.

19. Use tool to release screws and separate lift POM and front cover.
20. Use tool to release screws and separate hinge shield

21. Use tool to release screws and separate constant force springs from hinge shield.
22. Use tool to release screws and separate the site of constant force springs.